

Board Level Cooling - Slide On 5802



BOARD LEVEL COOLING - Slide On 5802

Slide On 5802 is a series of slide on board level heat sinks designed to cool DIP and TO-3 devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
580200B00000G	DIP
580200W00000G	DIP
560200B00000G	TO-3

HEAT SINK DETAILS

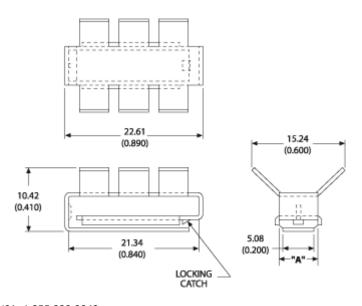
Property	Details
Material	Aluminum
Device Attachment Options	Slide On
Thermal Interface Material	-

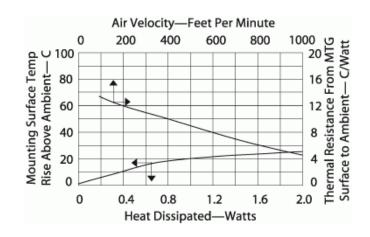
Property	Details
Heat Sink Width (mm)	15.24
Heat Sink Length (mm)	22.61
Heat Sink Height (mm)	10.42
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

Part Number	Finish	"A" Dim
580200B00000G	Black Anodize	6.35
580200W00000G	Dielectric Paint	6.35
560200B00000G	Black Anodize	7.87





USA: 1.855.322.2843 EUROPE: 39.051.764002 ASIA: 86.21.6115.2000 x8122

